

	<div>Kunden-Datenblatt- Leiterplatte Data Sheet - PCB</div>		Stand: 10.02.2015		
<div>Bezeichnung / Name:</div> <div>LP-Nr. / Board-Nr: _____ Bezeichnung / Name: _____</div> <div>Art.-Nr.: _____ Datei / File: _____ HWB _____</div>					
<div>Basis-Material / Ausführung / Laminat:</div> <div>FR4                      Polyimid                      FR4 / Polyimid                      TG: _____</div> <div>starr / rigid                      flex                      starr-flex / rigid-flex                      semiflex</div> <div>LP-Dicke / board thicknes:                      1,0mm                      1,6mm                      2,0mm                      2,4mm                      _____</div> <div>Lagenzahl / Layer counts:                      1-lagig / layer                      2-lagig / layers                      -lagig / layers                      Signalleitungen auf Innenlagen / Signal lines on the inside</div> <div>SMD-Best. / SMD-Pads:                      BS                      LS                      ohne / without</div> <div>Remark : ( BS = component side = top ) ( LS = solder side = bottom )</div>					
<div>Mechanik / Maße / Mechanic / Diameter:</div> <div>Einzelplatine / single board                      Nutzen- _____ fach / panel - fold                      Bohrungen / drillings: _____</div> <div>gefräst / milling                      geritzt / scoring                      _____</div> <div>Maße Einzel / Nutzen    Diameter Single / Panel                      _____ x _____ / _____ x _____ mm</div>					
<div>Metallisierung (Endstärke) / Plating thickness (final thickness):</div> <div>Kupfer-Endstärke / Copper thickness layer:                      ≥ 35µ                      _____</div> <div>Kupfer-Hülse / plated through holes:                      ≥ 20µ                      _____</div>					
<div>Oberfläche, Lack / Finish:</div> <div>HAL bleifrei                      ch. Sn ≥ 0,08µ                      ch. NiAu ≥ 0,05µ Au                      galv. NiAu ≥ 1,27µ Au                      _____</div> <div>Lötstoplack / Soldermask:                      BS                      LS                      Farbe / Colour: _____                      ohne / without</div> <div>Bestückungsdruck / Component notation:                      BS                      LS                      Farbe / Colour: _____                      ohne / without</div> <div>Via-Druck luftdicht / Via closed:                      BS                      LS                      ohne / without</div> <div>Abdeckmaske abziehbar / Peelable mask:                      BS                      LS                      ohne / without</div>					
<div>Prüfungen / Checks:</div> <div>Leiterbild / Layout:                      Sichtkontrolle                      AOI                      Elektr.-Test / electrical checks, Kennzeichnung: _____</div> <div>Sonstiges / other:                      Schliff (bild)                      Impedanzen, _____</div>					
<div>Klassifizierung / Classification:</div> <div>Leiterbreite / -abstand (µ) / kleinste Bohrung End-Ø (mm) / Lines width / -distance (µ) / smallest hole - final diameter (mm)</div> <div>K1 (Normal: ≥ 8mil / 0,4mm)                      K2 (Fein: ≥ 6mil / 0,3mm)                      K3 (Feinst: ≥ 5mil / 0,2mm)                      _____</div> <div>UL-Kennzeichnung und Datumskodierung / UL-marking and Date-Code</div>					
	Erstellt / made		Geprüft / checked		Freigegeben / released
Datum / Date:		Datum / Date:		Datum / Date:	
Name:		Name:		Name:	

Bemerkungen / Remarks: